

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Chou LI

Serial Number: To be determined

Division of application of US. 09/053, 741

Prior Group Art Unit: 3729

Filed: June 25, 2001

Prior Examiner: CHANG, R.

For: HEAT RESISTANT ELECTRONIC SYSTEMS AND CIRCUIT BOARD

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

June 25, 2001

Dear Sir:

Prior to issuing an action on the merits please amend the subject application as set forth below:

In the specification

Page 41, line 22, after "bottom." delete "(need figure?).delete".

Please renumber pages 56, 57, 58 ,59,60, 61, 62 and 63 as 55, 56, 57 , 58 , 59, 60, 61 and 62.

In the claims

Please cancel all claims, claims 1-43, and substitute therefor new claims 44-51:

44. A metal-matrix composite material comprising a base material reinforced by an additive which has a melting point of at least 300° C greater than that of the base material.

45. The composite as in claim 44 in which the base material is a metal base material which is reinforced by a strengthening additive to enhance said base material at least in more than two properties selected from the properties of mechanical strength, thermal stability and electrical properties.

46. The composite as in claim 44 in which the metal base is selected from the group consisting of aluminum, magnesium, titanium, iron, nickel, copper and gold.